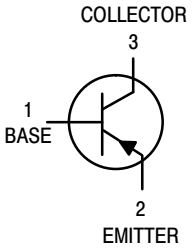
BC807-16LT1G, BC807-25LT1G, BC807-40LT1G

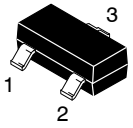
General Purpose Transistors

PNP Silicon

ON Semiconductor®

http://onsemi.com





SOT−23
CASE 318
STYLE 6

Features

- These Devices are Pb−Free, Halogen Free/BFR Free and are RoHS Compliant

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector − Emitter Voltage	V_{CEO}	−45	V
Collector − Base Voltage	V_{CBO}	−50	V
Emitter − Base Voltage	V_{EBO}	−5.0	V
Collector Current − Continuous	I_C	−500	mAdc

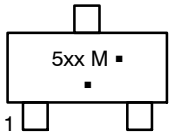
THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation FR−5 Board, (Note 1) T_A = 25°C Derate above 25°C	P_D	225 1.8	mW mW/°C
Thermal Resistance, Junction−to−Ambient	$R_{\theta JA}$	556	°C/W
Total Device Dissipation Alumina Substrate, (Note 2) T_A = 25°C Derate above 25°C	P_D	300 2.4	mW mW/°C
Thermal Resistance, Junction−to−Ambient	$R_{\theta JA}$	417	°C/W
Junction and Storage Temperature	T_J, T_{stg}	−55 to +150	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. FR−5 = 1.0 x 0.75 x 0.062 in.
2. Alumina = 0.4 x 0.3 x 0.024 in 99.5% alumina.

MARKING DIAGRAM



5xx = Device Code
xx = A1, B1, or C
M = Date Code*
▪ = Pb−Free Package

(Note: Microdot may be in either location)

*Date Code orientation and/or overbar may vary depending upon manufacturing location.

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted.)

Characteristic		Symbol	Min	Typ	Max	Unit
OFF CHARACTERISTICS						
Collector − Emitter Breakdown Voltage (I_C = −10 mA)		$V_{(BR)CEO}$	−45	−	−	V
Collector − Emitter Breakdown Voltage (V_{EB} = 0, I_C = −10 μA)		$V_{(BR)CES}$	−50	−	−	V
Emitter − Base Breakdown Voltage (I_E = −1.0 μA)		$V_{(BR)EBO}$	−5.0	−	−	V
Collector Cutoff Current		I_{CBO}				
(V_{CB} = −20 V)			−	−	−100	nA
(V_{CB} = −20 V, T_J = 150°C)			−	−	−5.0	μA
ON CHARACTERISTICS						
DC Current Gain		h_{FE}				−
(I_C = −100 mA, V_{CE} = −1.0 V)	BC807−16		100	−	250	
	BC807−25		160	−	400	
	BC807−40		250	−	600	
(I_C = −500 mA, V_{CE} = −1.0 V)			40	−	−	
Collector − Emitter Saturation Voltage (I_C = −500 mA, I_B = −50 mA)		$V_{CE(sat)}$	−	−	−0.7	V
Base − Emitter On Voltage (I_C = −500 mA, I_B = −1.0 V)		$V_{BE(on)}$	−	−	−1.2	V
SMALL−SIGNAL CHARACTERISTICS						
Current − Gain − Bandwidth Product (I_C = −10 mA, V_{CE} = −5.0 Vdc, f = 100 MHz)		f_T	100	−	−	MHz
Output Capacitance (V_{CB} = −10 V, f = 1.0 MHz)		C_{obo}	−	10	−	pF

ORDERING INFORMATION

Device	Specific Marking	Package	Shipping†
BC807−16LT1G	5A1	SOT−23 (Pb−Free)	3000/Tape & Reel
BC807−16LT3G		SOT−23 (Pb−Free)	10,000/Tape & Reel
BC807−25LT1G	5B1	SOT−23 (Pb−Free)	3000/Tape & Reel
BC807−25LT3G		SOT−23 (Pb−Free)	10,000/Tape & Reel
BC807−40LT1G	5C	SOT−23 (Pb−Free)	3000/Tape & Reel
BC807−40LT3G		SOT−23 (Pb−Free)	10,000/Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

TYPICAL CHARACTERISTICS − BC807−16LT1

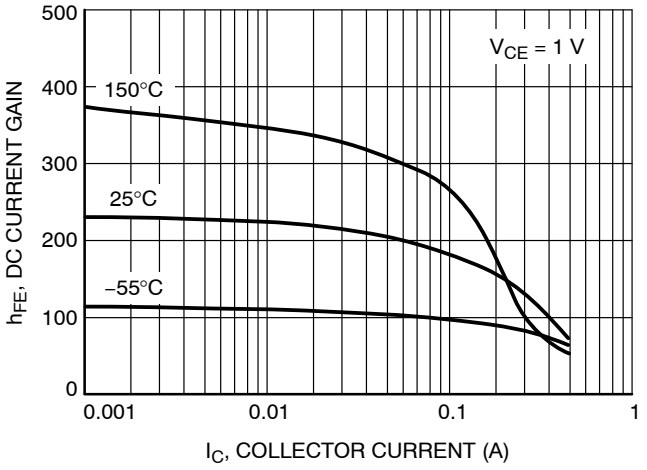


Figure 1. DC Current Gain vs. Collector Current

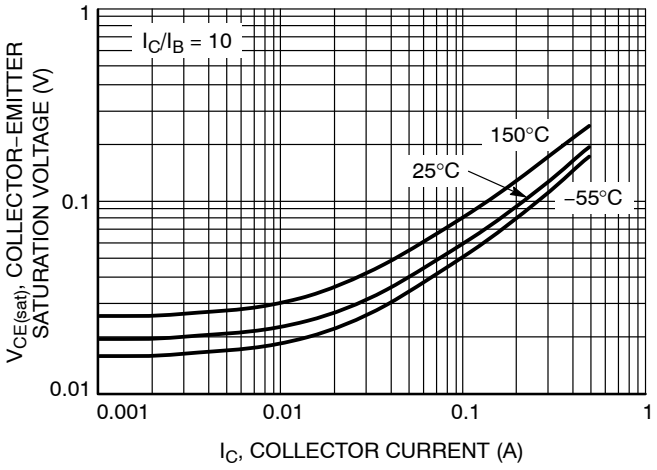


Figure 2. Collector Emitter Saturation Voltage vs. Collector Current

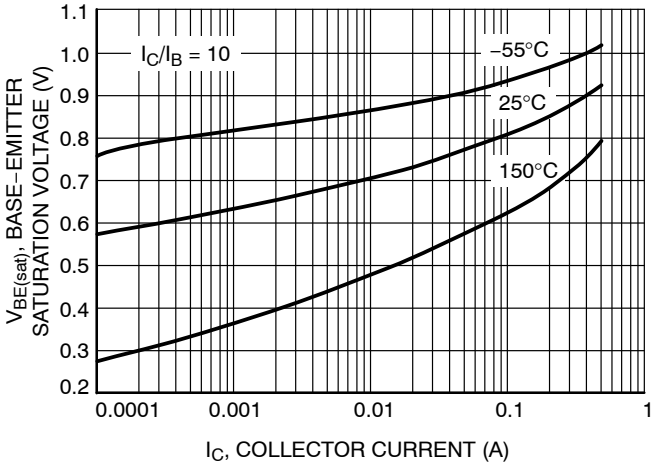


Figure 3. Base Emitter Saturation Voltage vs. Collector Current

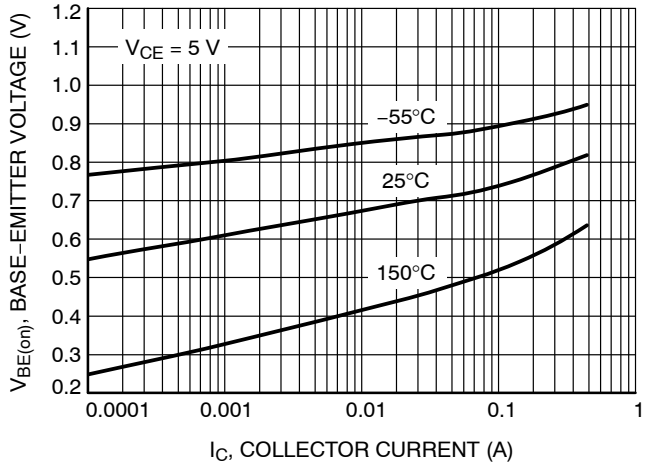


Figure 4. Base Emitter Voltage vs. Collector Current

TYPICAL CHARACTERISTICS − BC807−16LT1

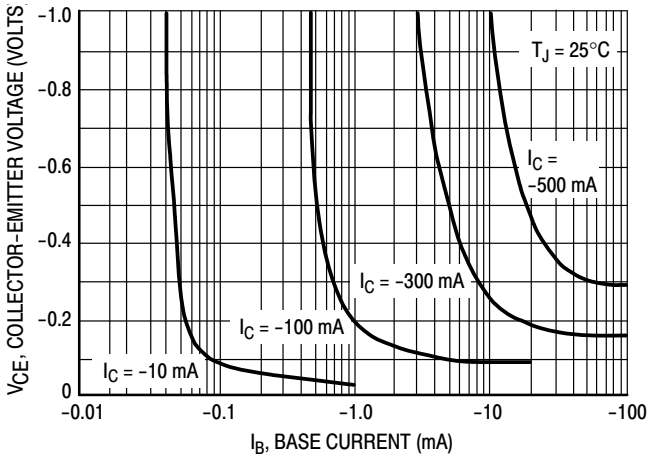


Figure 5. Saturation Region

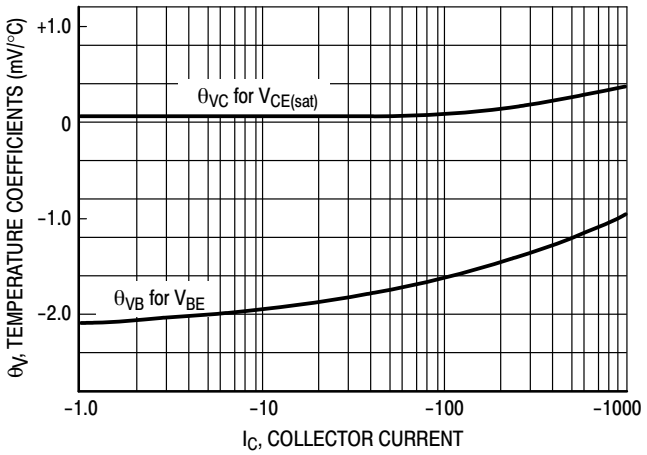


Figure 6. Temperature Coefficients

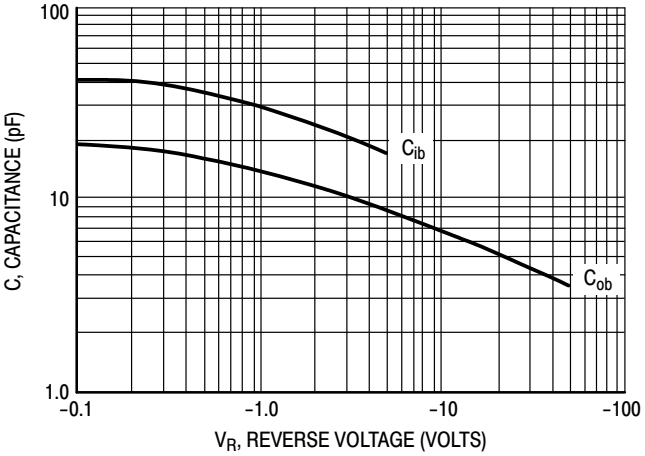


Figure 7. Capacitances

TYPICAL CHARACTERISTICS − BC807−25LT1

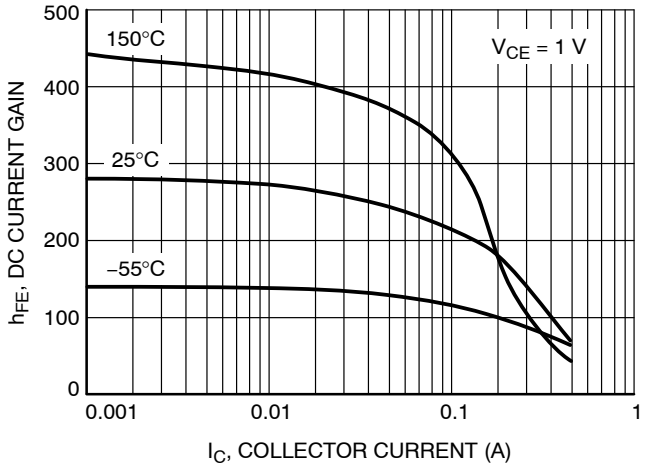


Figure 8. DC Current Gain vs. Collector Current

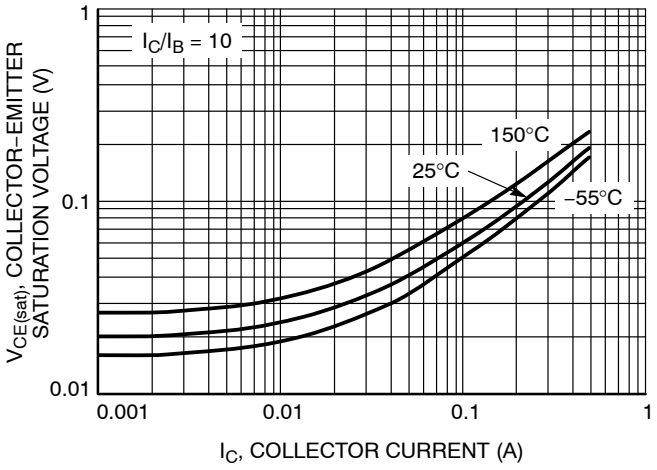


Figure 9. Collector Emitter Saturation Voltage vs. Collector Current

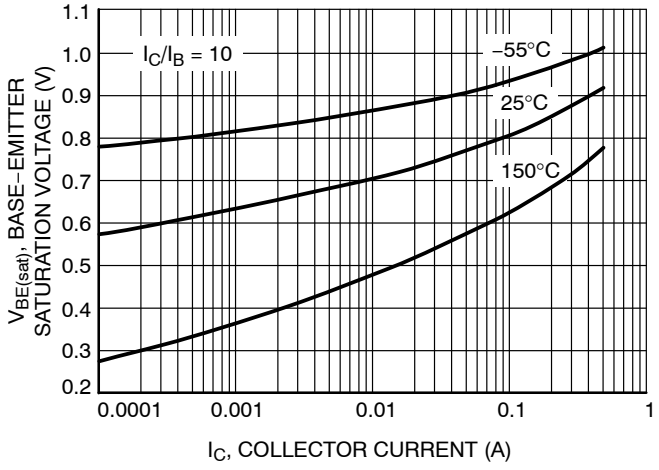


Figure 10. Base Emitter Saturation Voltage vs. Collector Current

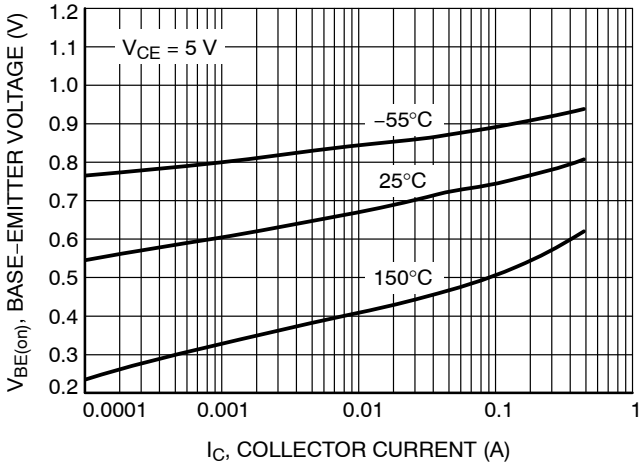


Figure 11. Base Emitter Voltage vs. Collector Current

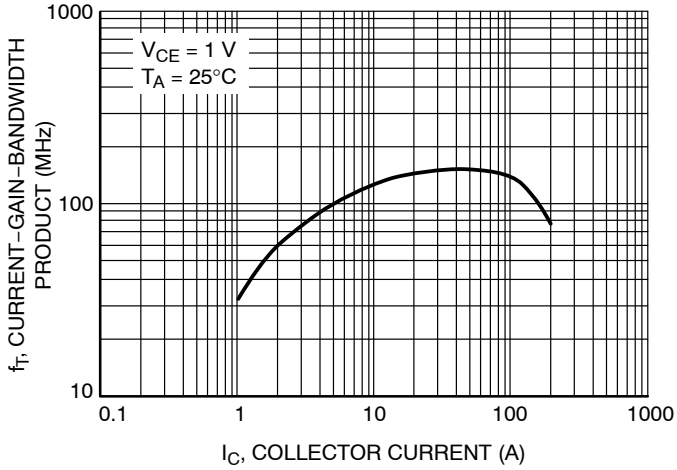


Figure 12. Current Gain Bandwidth Product vs. Collector Current

TYPICAL CHARACTERISTICS − BC807−25LT1

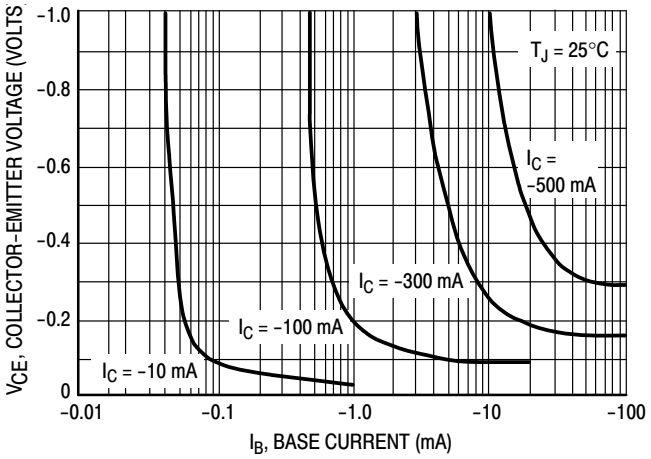


Figure 13. Saturation Region

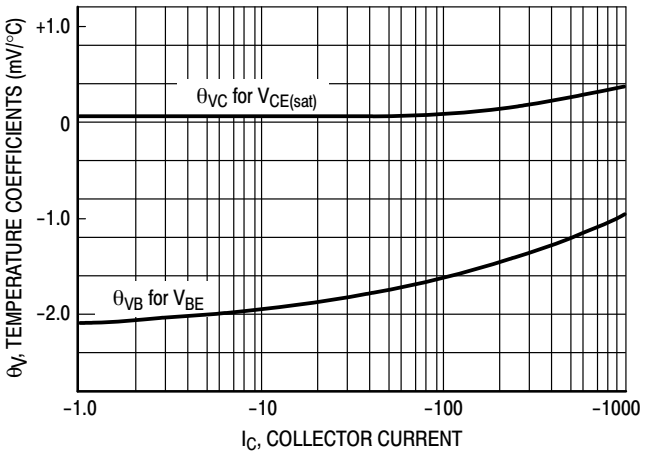


Figure 14. Temperature Coefficients

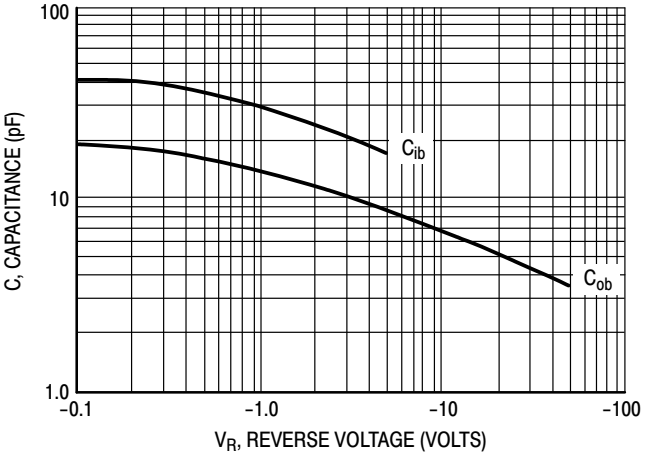


Figure 15. Capacitances

TYPICAL CHARACTERISTICS − BC807−40LT1

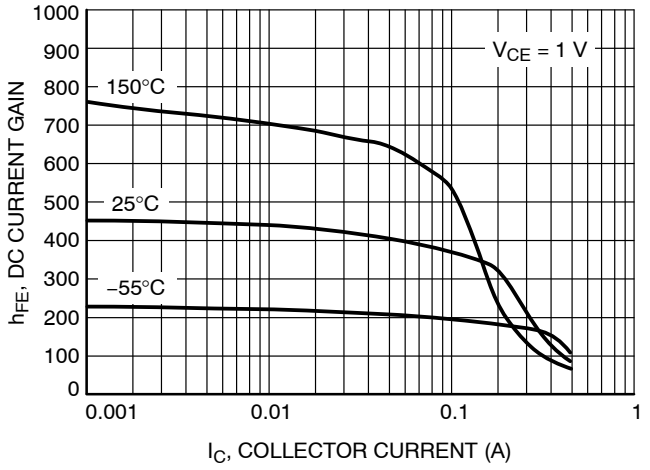


Figure 16. DC Current Gain vs. Collector Current

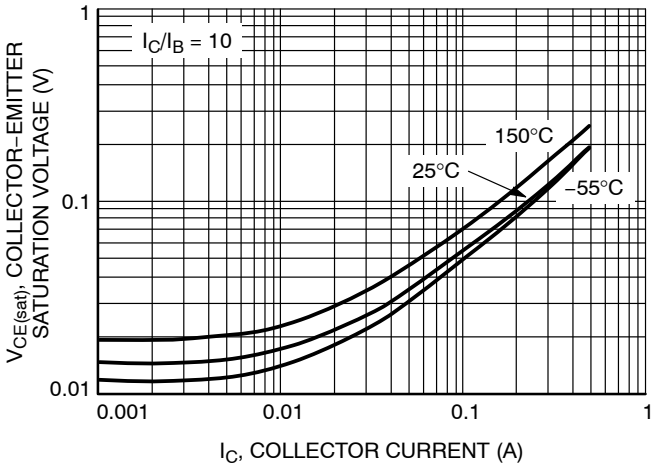


Figure 17. Collector Emitter Saturation Voltage vs. Collector Current

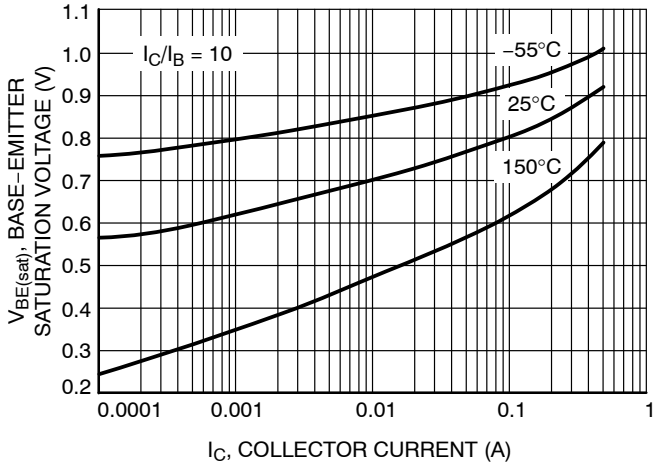


Figure 18. Base Emitter Saturation Voltage vs. Collector Current

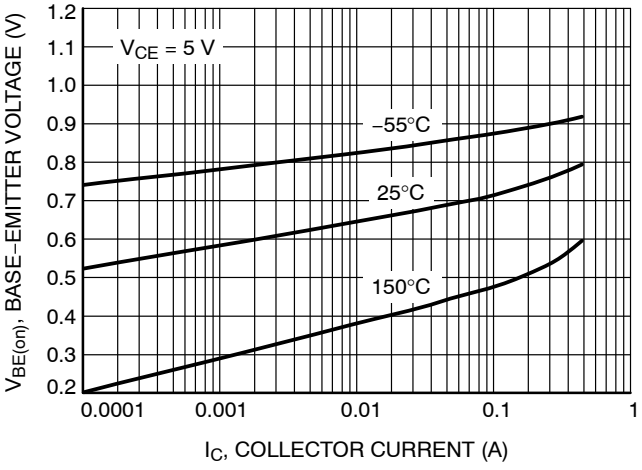


Figure 19. Base Emitter Voltage vs. Collector Current

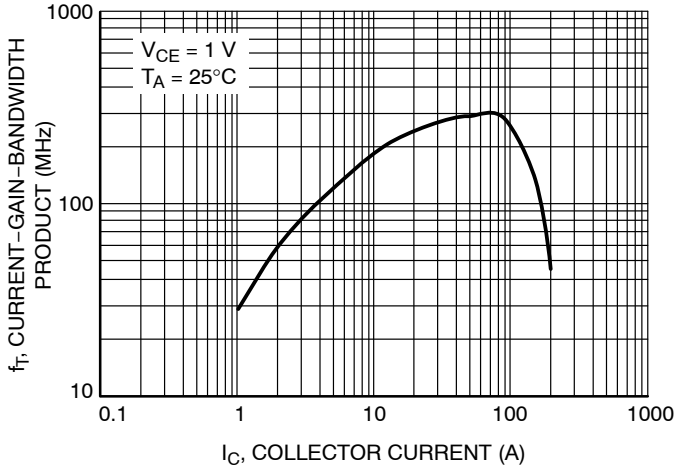


Figure 20. Current Gain Bandwidth Product vs. Collector Current

TYPICAL CHARACTERISTICS − BC807−40LT1

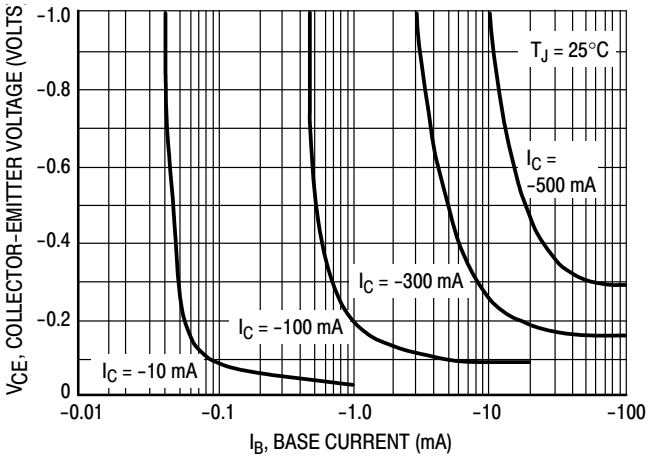


Figure 21. Saturation Region

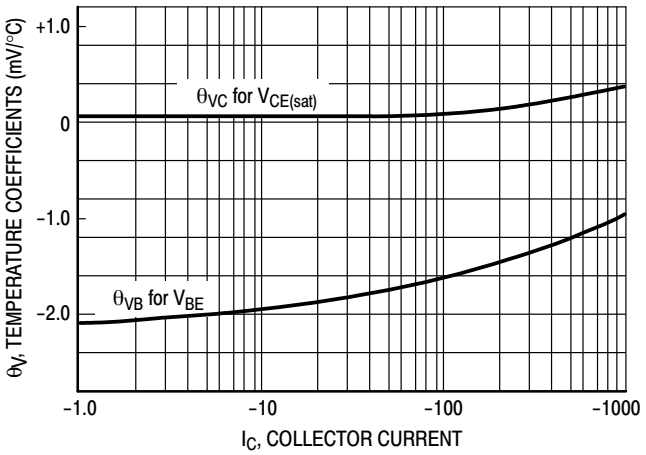


Figure 22. Temperature Coefficients

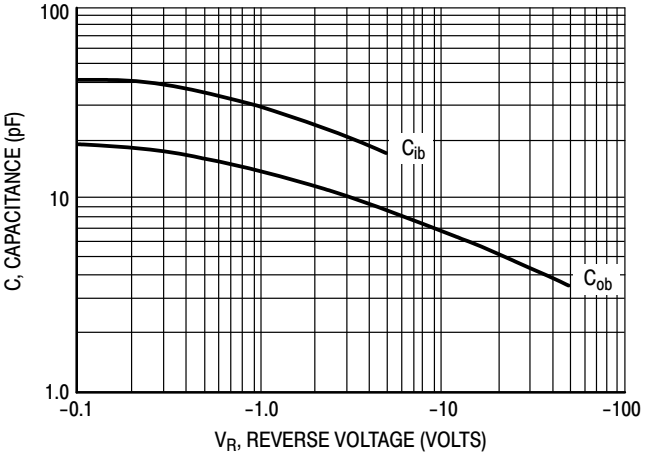


Figure 23. Capacitances

TYPICAL CHARACTERISTICS − BC807−16LT1, BC807−25LT1, BC807−40LT1

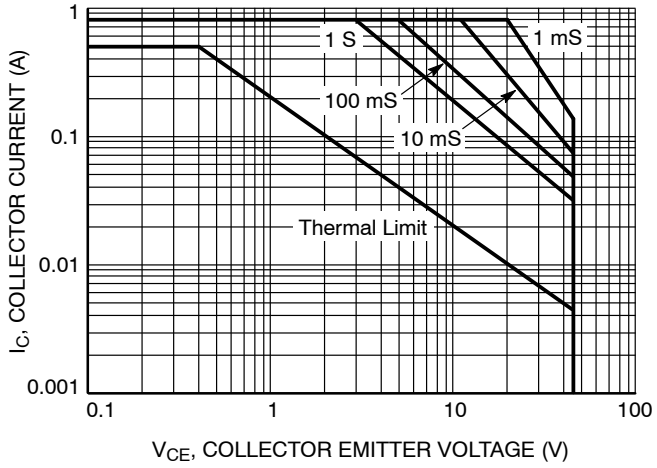
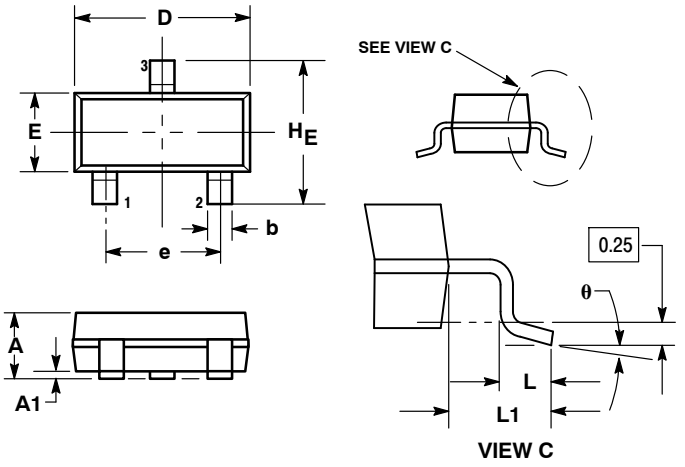


Figure 24. Safe Operating Area

PACKAGE DIMENSIONS

SOT−23 (TO−236)
CASE 318−08
ISSUE AN



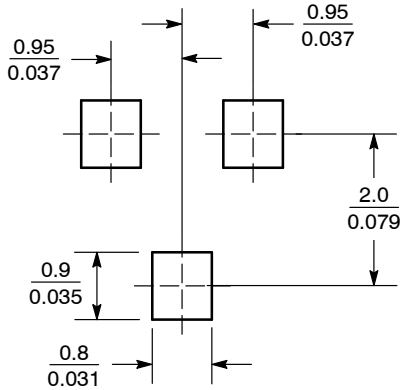
VIEW C

NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
4. 318−01 THRU −07 AND −09 OBSOLETE, NEW STANDARD 318−08.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
A	0.89	1.00	1.11	0.035	0.040	0.044
A1	0.01	0.06	0.10	0.001	0.002	0.004
b	0.37	0.44	0.50	0.015	0.018	0.020
c	0.09	0.13	0.18	0.003	0.005	0.007
D	2.80	2.90	3.04	0.110	0.114	0.120
E	1.20	1.30	1.40	0.047	0.051	0.055
e	1.78	1.90	2.04	0.070	0.075	0.081
L	0.10	0.20	0.30	0.004	0.008	0.012
L1	0.35	0.54	0.69	0.014	0.021	0.029
H_E	2.10	2.40	2.64	0.083	0.094	0.104

STYLE 6:
PIN 1. BASE
2. EMITTER
3. COLLECTOR

SOLDERING FOOTPRINT*



*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:
Literature Distribution Center for ON Semiconductor
P.O. Box 5163, Denver, Colorado 80217 USA
Phone: 303−675−2175 or 800−344−3860 Toll Free USA/Canada
Fax: 303−675−2176 or 800−344−3867 Toll Free USA/Canada
Email: orderlit@onsemi.com

N. American Technical Support: 800−282−9855 Toll Free USA/Canada
Europe, Middle East and Africa Technical Support:
Phone: 421 33 790 2910
Japan Customer Focus Center
Phone: 81−3−5773−3850

ON Semiconductor Website: **www.onsemi.com**

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative